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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Sensitive Gate Triacs

Silicon Bidirectional Thyristors

Designed for high volume, low cost, industrial and consumer applications such as motor control; process control; temperature, light and speed control.

Features

- Small Size Surface Mount DPAK Package
- Passivated Die for Reliability and Uniformity
- Four-Quadrant Triggering
- Blocking Voltage to 600 V
- On-State Current Rating of 4.0 Amperes RMS at 93°C
- Low Level Triggering and Holding Characteristics
- Epoxy Meets UL 94 V-0 @ 0.125 in
- ESD Ratings: Human Body Model, 3B > 8000 V Machine Model, C > 400 V
- Pb-Free Packages are Available

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage (Note 1) $(T_J = -40 \text{ to } 110^{\circ}\text{C}, \text{ Sine Wave}, 50 \text{ to } 60 \text{ Hz}, \text{ Gate Open})$	V _{DRM,} V _{RRM}	600	V
On–State RMS Current (Full Cycle Sine Wave, 60 Hz, T _C = 93°C)	I _{T(RMS)}	4.0	Α
Peak Non-Repetitive Surge Current (One Full Cycle, 60 Hz, T _J = 110°C)	I _{TSM}	40	Α
Circuit Fusing Consideration (t = 8.3 msec)	I ² t	6.6	A ² sec
Peak Gate Power (Pulse Width ≤ 10 μsec, T _C = 93°C)	P _{GM}	2.0	W
Average Gate Power (t = 8.3 msec, T _C = 93°C)	P _{G(AV)}	1.0	W
Peak Gate Current (Pulse Width \leq 20 µsec, T _C = 93°C)	I _{GM}	4.0	Α
Peak Gate Voltage (Pulse Width \leq 20 μ sec, T_C = 93°C)	V_{GM}	5.0	V
Operating Junction Temperature Range	TJ	-40 to 110	°C
Storage Temperature Range	T _{stg}	-40 to 150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

 V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the device are exceeded.



Littelfuse.com

TRIACS 4.0 AMPERES RMS 600 VOLTS



MARKING DIAGRAMS

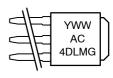


DPAK CASE 369C STYLE 6





DPAK-3 CASE 369D STYLE 6



Y = Year

WW = Work Week

AC4DLM = Device Code

G = Pb-Free Package

PIN ASSIGNMENT			
1	Main Terminal 1		
2	Main Terminal 2		
3	Gate		
4	Main Terminal 2		

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance - Junction-to-Case - Junction-to-Ambient - Junction-to-Ambient (Note 2)	R _{θJC} R _{θJA} R _{θJA}	3.5 88 80	°C/W
Maximum Lead Temperature for Soldering Purposes (Note 3)	T_L	260	°C

FI FCTRICAL CHARACTERISTICS (T = 25°C unless otherwise noted: Flectricals apply in both directions)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Peak Repetitive Blocking Current $(V_D = Rated\ V_{DRM},\ V_{RRM};\ Gate\ Open) \\ T_J = 25^{\circ}C \\ T_J = 110^{\circ}C$	I _{DRM,} I _{RRM}		_ _	0.01 2.0	mA
ON CHARACTERISTICS		•			
Peak On-State Voltage (Note 4) - (I _{TM} = ±6.0 A)	V_{TM}	-	1.3	1.6	V
Gate Trigger Current (Continuous dc) (V_D = 12 V, R_L = 100 Ω) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-) MT2(-), G(+)	I _{GT}	- - - -	1.8 2.1 2.4 4.2	3.0 3.0 3.0 5.0	mA
Gate Trigger Voltage (Continuous dc) (V_D = 12 V, R_L = 100 Ω) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-) MT2(-), G(+)	V _{GT}	0.5 0.5 0.5 0.5	0.62 0.57 0.65 0.74	1.3 1.3 1.3 1.3	V
Gate Non-Trigger Voltage $(V_D = 12 \text{ V}, R_L = 100 \ \Omega, T_J = 110^{\circ}\text{C})$ MT2(+), G(+); MT2(+), G(-); MT2(-), G(-); MT2(-), G(+)	$V_{\sf GD}$	0.1	0.4	_	V
Holding Current $(V_D = 12 \text{ V}, \text{ Gate Open, Initiating Current} = \pm 200 \text{ mA})$	Iн	-	1.5	15	mA
$ \begin{array}{llllllllllllllllllllllllllllllllllll$	IL	- - -	1.75 5.2 2.1 2.2	10 10 10 10	mA
DYNAMIC CHARACTERISTICS					
Rate of Change of Commutating Current $(V_D=200~V,~I_{TM}=1.8~A,~Commutating~dv/dt=1.0~V/\mu sec,\\ T_J=110^{\circ}C,~f=250~Hz,~CL=5.0~\mu fd,~LL=80~mH,~RS=56~\Omega,\\ CS=0.03~\mu fd)~With~snubber~see~Figure~11$	di/dt(c)	-	3.0	-	A/ms
Critical Rate of Rise of Off–State Voltage $(V_D=0.67~X~Rated~V_{DRM},~Exponential~Waveform,~Gate~Open,~T_J=110^{\circ}C)$	dv/dt	10	-	-	V/μs

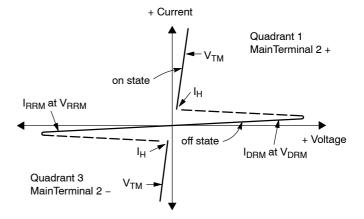
These ratings are applicable when surface mounted on the minimum pad sizes recommended.
 1/8" from case for 10 seconds.
 Pulse Test: Pulse Width ≤ 2.0 msec, Duty Cycle ≤ 2%.

ORDERING INFORMATION

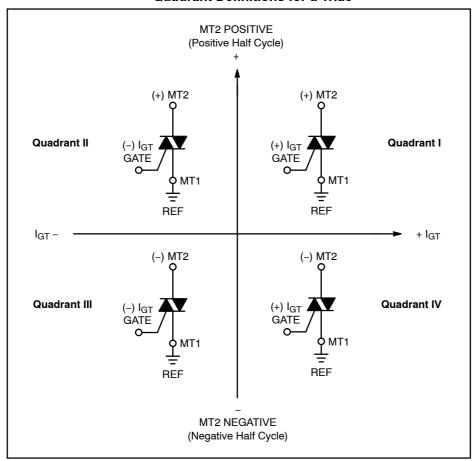
Device	Package Type	Package	Shipping
MAC4DLM-001	DPAK-3	369D	75 Units / Rail
MAC4DLM-001G	DPAK-3 (Pb-Free)	369D	75 Units / Rail
MAC4DLMT4	DPAK	369C	2500 / Tape & Reel
MAC4DLMT4G	DPAK (Pb-Free)	369C	2500 / Tape & Reel

Voltage Current Characteristic of Triacs (Bidirectional Device)

Symbol	Parameter
V_{DRM}	Peak Repetitive Forward Off-State Voltage
I _{DRM}	Peak Forward Blocking Current
V_{RRM}	Peak Repetitive Reverse Off-State Voltage
I _{RRM}	Peak Reverse Blocking Current
V_{TM}	Maximum On-State Voltage
I _H	Holding Current



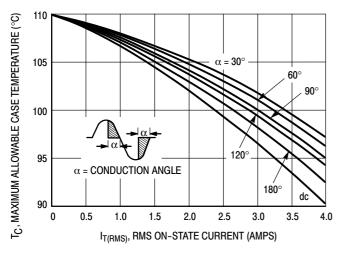
Quadrant Definitions for a Triac



All polarities are referenced to MT1.

With in-phase signals (using standard AC lines) quadrants I and III are used.

6.0

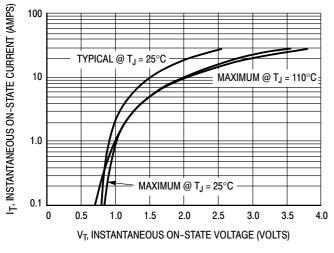


P(AV), AVERAGE POWER DISSIPATION (WATTS) 180° 5.0 120° 4.0 α = CONDUCTION ANGLE 3.0 2.0 60° α = 30° 1.0 0 0.5 3.5 1.0 1.5 2.0 2.5 3.0 4.0 I_{T(RMS)}, RMS ON-STATE CURRENT (AMPS)

dc

Figure 1. RMS Current Derating

Figure 2. On-State Power Dissipation



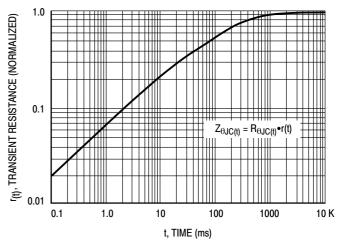
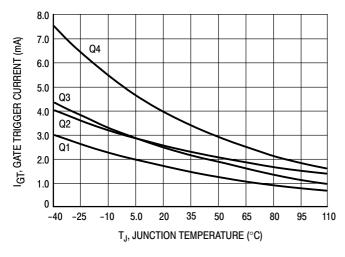


Figure 3. On-State Characteristics

Figure 4. Transient Thermal Response



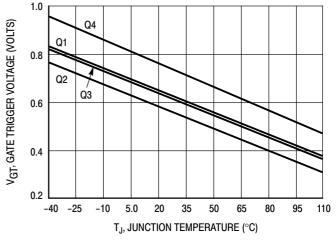
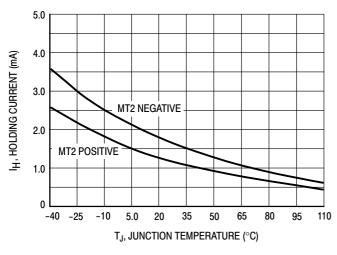


Figure 5. Typical Gate Trigger Current versus **Junction Temperature**

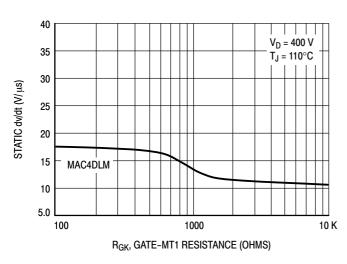
Figure 6. Typical Gate Trigger Voltage versus **Junction Temperature**



12 10 IL, LATCHING CURRENT (mA) 8.0 Q2 6.0 4.0 2.0 0 -40 -25 -10 5.0 35 95 20 50 65 80 110 T_J, JUNCTION TEMPERATURE (°C)

Figure 7. Typical Holding Current versus Junction Temperature

Figure 8. Typical Latching Current versus Junction Temperature



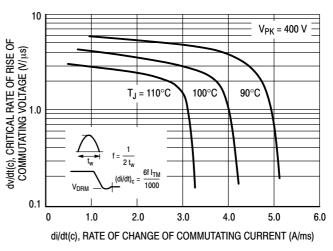
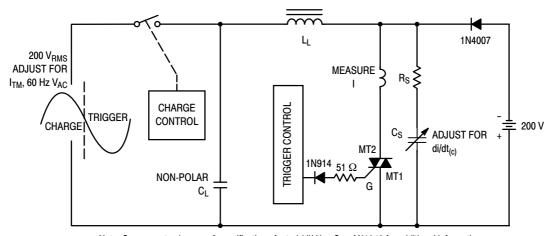


Figure 9. Minimum Exponential Static dv/dt versus Gate-MT1 Resistance

Figure 10. Critical Rate of Rise of Commutating Voltage

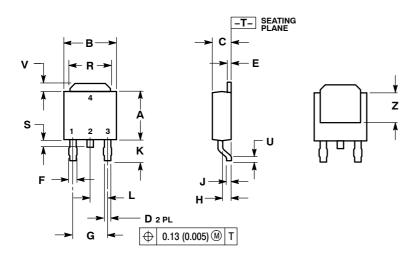


Note: Component values are for verification of rated (di/dt) $_{\text{\tiny C}}.$ See AN1048 for additional information.

Figure 11. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Current (di/dt)_c

PACKAGE DIMENSIONS

DPAK CASE 369C **ISSUE O**

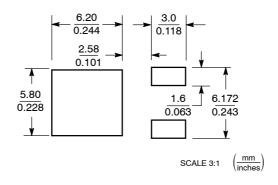


- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.245	5.97	6.22
В	0.250	0.265	6.35	6.73
С	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.180 BSC		4.58	BSC
Н	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.090 BSC		2.29 BSC	
R	0.180	0.215	4.57	5.45
S	0.025	0.040	0.63	1.01
U	0.020		0.51	
V	0.035	0.050	0.89	1.27
Z	0.155		3.93	

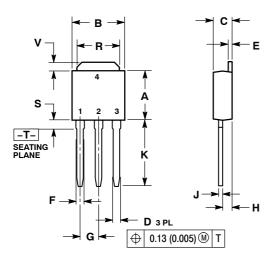
STYLE 6: PIN 1. MT1 2. MT2 3. GATE 4. MT2

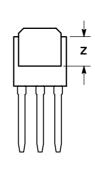
SOLDERING FOOTPRINT



PACKAGE DIMENSIONS

DPAK-3 CASE 369D-01 **ISSUE B**





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.245	5.97	6.35
В	0.250	0.265	6.35	6.73
С	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090 BSC		2.29 BSC	
Н	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
٧	0.035	0.050	0.89	1.27
7	0 155		3.93	

STYLE 6:

PIN 1. MT1 MT2 2.

3. GATE

Littelfuse products are not designed for, and shall not be used for, any purpose (including, without limitation, automotive, military, aerospace, medical, life-saving, life-sustaining or nuclear facility applications, devices intended for surgical implant into the body, or any other application in which the failure or lack of desired operation of the product may result in personal injury, death, or property damage) other than those expressly set forth in applicable Littelfuse product documentation. Warranties granted by Littelfuse shall be deemed void for products used for any purpose not expressly set forth in applicable Littelfuse documentation. Littelfuse shall not be liable for any claims or damages arising out of products used in applications not expressly intended by Littelfuse as set forth in applicable Littelfuse documentation. The sale and use of Littelfuse products is subject to Littelfuse Terms and Conditions of Sale, unless otherwise agreed by Littelfuse.

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